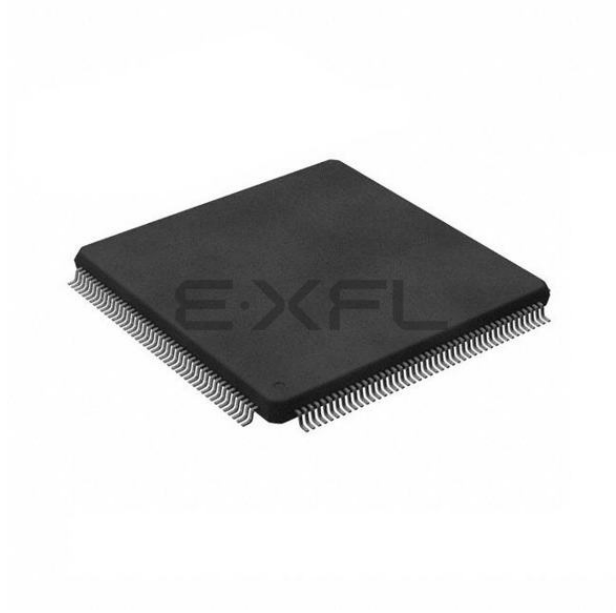

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CSIO, EBI/EMI, I²C, LINbus, SD, SPI, UART/USART, USB
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	152
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2c38j0agv2000a

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
50	40	35	L1	P3E SCK13_0 (SCL13_0) RTO05_0 (PPG04_0) TIOA5_1 MAD19_0 MNREX_0	G	I
51	41	-	L2	P5D SIN10_1 TIOB11_2 INT01_2 MADATA29_0 I2SMCLK0_0	E	K
52	42	-	L3	P5E SOT10_1 (SDA10_1) TIOA12_2 MADATA30_0 I2SDO0_0	E	I
53	43	-	M2	P5F SCK10_1 (SCL10_1) TIOB12_2 MADATA31_0 I2SWS0_0	E	I
54	44	36	M1	VSS	-	-
55	45	37	N1	VCC	-	-
56	46	38	N2	P40 SIN3_1 RTO10_0 (PPG10_0) TIOA0_0 AIN0_0 INT23_0 MCSX7_0	G	K
57	47	39	N3	P41 SOT3_1 (SDA3_1) RTO11_0 (PPG10_0) TIOA1_0 BIN0_0 MCSX6_0	G	I
58	48	40	M3	P42 SCK3_1 (SCL3_1) RTO12_0 (PPG12_0) TIOA2_0 ZIN0_0 MCSX5_0	G	I

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
135	111	91	H11	P1D AN13 SCK12_0 (SCL12_0) TIOB5_2 TRACED3	F	N
136	-	-	-	VSS	-	-
137	-	-	-	VCC	-	-
138	112	-	G13	PB4 AN20 SIN8_1 TIOA11_1 INT10_1 TRACED4	F	O
139	113	-	F14	PB5 AN21 SOT8_1 (SDA8_1) TIOB11_1 INT11_1 TRACED5	F	O
140	114	-	G12	PB6 AN22 SCK8_1 (SCL8_1) TIOA12_1 TRACED6	F	N
141	115	-	G11	PB7 AN23 TIOB12_1 TRACED7	F	N
142	116	92	G10	P1E AN14 TIOA8_1 INT26_1 MAD10_0	F	M
143	117	93	G9	P1F AN15 RTS5_0 TIOB8_1 INT27_1 MAD11_0	F	M
144	118	94	F10	P2A AN24 CTS5_0 MAD12_0	F	L
145	119	95	F11	P29 AN25 SCK5_0 (SCL5_0) MAD13_0	F	L

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Base Timer 13	TIOA13_0	Base Timer ch 13 TIOA pin	7	7	7	D1
	TIOA13_1		154	124	100	E12
	TIOA13_2		34	24	-	G6
	TIOB13_0	Base Timer ch 13 TIOB pin	31	22	19	G4
	TIOB13_1		155	125	101	E13
	TIOB13_2		35	25	-	H4
Base Timer 14	TIOA14_0	Base Timer ch 14 TIOA pin	183	151	121	D8
	TIOA14_1		89	74	-	M9
	TIOA14_2		204	-	-	-
	TIOB14_0	Base Timer ch 14 TIOB pin	182	150	120	C8
	TIOB14_1		90	75	-	L9
	TIOB14_2		203	-	-	-
Base Timer 15	TIOA15_0	Base Timer ch 15 TIOA pin	187	155	125	B7
	TIOA15_1		78	63	-	K5
	TIOA15_2		206	-	-	-
	TIOB15_0	Base timer ch 15 TIOB pin	186	154	124	F8
	TIOB15_1		79	64	-	K6
	TIOB15_2		205	-	-	-
Debugger	SWCLK	Serial wire debug interface clock input pin	165	135	111	A12
	SWDIO	Serial wire debug interface data input/ output pin	167	137	113	B12
	SWO	Serial wire viewer output pin	168	138	114	B11
	TCK	JTAG test clock input pin	165	135	111	A12
	TDI	JTAG test data input pin	166	136	112	C12
	TDO	JTAG debug data output pin	168	138	114	B11
	TMS	JTAG test mode state input/output pin	167	137	113	B12
	TRACECLK	Trace CLK output pin of ETM/HTM	131	107	87	H12
	TRACED0	Trace data output pin of ETM/ Trace data output pin of HTM	132	108	88	H14
	TRACED1		133	109	89	G14
	TRACED2		134	110	90	H13
	TRACED3		135	111	91	H11
	TRACED4	Trace data output pin of HTM	138	112	-	G13
	TRACED5		139	113	-	F14
	TRACED6		140	114	-	G12
	TRACED7		141	115	-	G11
	TRACED8		119	-	-	-
	TRACED9		120	-	-	-
	TRACED10		121	-	-	-
	TRACED11		122	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
External bus	MADATA00_0	External bus interface data bus (address/data multiplex bus)	2	2	2	B2
	MADATA01_0		3	3	3	C2
	MADATA02_0		4	4	4	C3
	MADATA03_0		5	5	5	D5
	MADATA04_0		6	6	6	D2
	MADATA05_0		7	7	7	D1
	MADATA06_0		8	8	8	D3
	MADATA07_0		9	9	9	D4
	MADATA08_0		14	13	10	E5
	MADATA09_0		15	14	11	F1
	MADATA10_0		16	15	12	F2
	MADATA11_0		17	16	13	F3
	MADATA12_0		18	17	14	F4
	MADATA13_0		23	18	15	F5
	MADATA14_0		24	19	16	F6
	MADATA15_0		25	20	17	G2
	MADATA16_0		10	-	-	-
	MADATA17_0		11	-	-	-
	MADATA18_0		12	-	-	-
	MADATA19_0		13	-	-	-
	MADATA20_0		19	-	-	-
	MADATA21_0		20	-	-	-
	MADATA22_0		21	-	-	-
	MADATA23_0		22	-	-	-
	MADATA24_0		26	-	-	-
	MADATA25_0		27	-	-	-
	MADATA26_0		28	-	-	-
	MADATA27_0		29	-	-	-
	MADATA28_0		33	-	-	-
	MADATA29_0		51	-	-	-
	MADATA30_0		52	-	-	-
	MADATA31_0		53	-	-	-
	MDQM0_0	External bus interface byte mask signal output pin	30	21	18	G3
	MDQM1_0		31	22	19	G4
	MDQM2_0		34	-	-	-
	MDQM3_0		35	-	-	-
	MALE_0	External bus interface address latch enable output signal for multiplex	211	171	139	C4
	MRDY_0	External bus interface external RDY input signal	80	65	55	L6

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
External bus	MCLKOUT_0	External bus interface external clock output pin	32	23	20	G5
	MNALE_0	External bus interface ALE signal to control NAND flash output pin	47	37	32	K2
	MNCLE_0	External bus interface CLE signal to control NAND flash output pin	48	38	33	K3
	MNREX_0	External bus interface read enable signal to control NAND flash	50	40	35	L1
	MNWEX_0	External bus interface write enable signal to control NAND flash	49	39	34	K4
	MOEX_0	External bus interface read enable signal for SRAM	209	169	137	C5
	MWEX_0	External bus interface write enable signal for SRAM	210	170	138	B4
	MSDCLK_0	SDRAM interface SDRAM clock output pin	90	75	-	L9
	MSDCKE_0	SDRAM interface SDRAM clock enable pin	89	74	-	M9
	MRASX_0	SDRAM interface SDRAM column active strobe pin	85	70	-	N8
	MCASX_0	SDRAM interface SDRAM row active strobe pin	86	71	-	M8
	MSDWEX_0	SDRAM interface SDRAM write enable pin	87	72	-	N9
External interrupt	INT00_0	External interrupt request 00 input pin	2	2	2	B2
	INT00_1		38	28	23	H3
	INT00_2		19	-	-	-
	INT01_0	External interrupt request 01 input pin	7	7	7	D1
	INT01_1		41	31	26	H6
	INT01_2		51	41	-	L2
	INT02_0	External interrupt request 02 input pin	14	13	10	E5
	INT02_1		42	32	27	J5
	INT02_2		26	-	-	-
	INT03_0	External interrupt request 03 input pin	17	16	13	F3
	INT03_1		43	33	28	J4
	INT03_2		34	24	-	G6
	INT04_0	External interrupt request 04 input pin	59	49	41	L4
	INT04_1		100	83	67	M11
	INT04_2		65	-	-	-
	INT05_0	External interrupt request 05 input pin	70	55	47	L5
	INT05_1		86	71	-	M8
	INT05_2		68	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Multi-Function Serial 7	SIN7_0	Multi-function serial interface ch 7 input pin	14	13	10	E5
	SIN7_1		103	-	-	-
	SOT7_0 (SDA7_0)	Multi-function serial interface ch 7 output pin. This pin operates as SOT7 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA7 when it is used in an I²C (operation mode 4).	15	14	11	F1
	SOT7_1 (SDA7_1)		102	-	-	-
	SCK7_0 (SCL7_0)	Multi-function serial interface ch 7 clock I/O pin. This pin operates as SCK7 when it is used in a CSIO (operation mode 2) and as SCL7 when it is used in an I²C (operation mode 4).	16	15	12	F2
	SCK7_1 (SCL7_1)		101	-	-	-
	SCS70_0	Multi-function serial interface ch 7 chip select 0 input/output pin	17	16	13	F3
	SCS70_1		94	-	-	-
	SCS71_0	Multi-function serial interface ch 7 chip select 1 input/output pin	18	17	14	F4
	SCS71_1		95	-	-	-
	SCS72_0	Multi-function serial interface ch 7 chip select 2 input/output pin	10	10	-	E2
	SCS72_1		68	-	-	-
	SCS73_0	Multi-function serial interface ch 7 chip select 3 input/output pin	11	11	-	E3
	SCS73_1		69	-	-	-
Multi-Function Serial 8	SIN8_0	Multi-function serial interface ch 8 input pin	91	76	60	K9
	SIN8_1		138	112	-	G13
	SOT8_0 (SDA8_0)	Multi-function serial interface ch 8 output pin. This pin operates as SOT8 when it is used in a UART/CSIO/LIN (operation modes 0 to 3) and as SDA8 when it is used in an I²C (operation mode 4).	92	77	61	P10
	SOT8_1 (SDA8_1)		139	113	-	F14
	SCK8_0 (SCL8_0)	Multi-function serial interface ch 8 clock I/O pin. This pin operates as SCK8 when it is used in a CSIO (operation mode 2) and as SCL8 when it is used in an I²C (operation mode 4).	93	78	62	N10
	SCK8_1 (SCL8_1)		140	114	-	G12

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Multi-Function Timer 0	DTTI0X_0	Input signal controlling waveform generator outputs RTO00 to RTO05 of Multi-Function Timer 0.	44	34	29	J3
	DTTI0X_1		21	-	-	-
	FRCK0_0	16-bit free-run timer ch 0 external clock input pin	37	27	22	J1
	FRCK0_1		29	-	-	-
	IC00_0	16-bit input capture input pin of Multi-Function Timer 0. ICxx describes channel number.	43	33	28	J4
	IC00_1		22	-	-	-
	IC01_0		42	32	27	J5
	IC01_1		26	-	-	-
	IC02_0		41	31	26	H6
	IC02_1		27	-	-	-
	IC03_0		38	28	23	H3
	IC03_1		28	-	-	-
	RTO00_0 (PPG00_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG00 when it is used in PPG0 output modes.	45	35	30	J2
	RTO00_1 (PPG00_1)		10	10	-	E2
	RTO01_0 (PPG00_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG00 when it is used in PPG0 output modes.	46	36	31	K1
	RTO01_1 (PPG00_1)		11	11	-	E3
	RTO02_0 (PPG02_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG02 when it is used in PPG0 output modes.	47	37	32	K2
	RTO02_1 (PPG02_1)		12	12	-	E4
	RTO03_0 (PPG02_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG02 when it is used in PPG0 output modes.	48	38	33	K3
	RTO03_1 (PPG02_1)		13	-	-	-
	RTO04_0 (PPG04_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG04 when it is used in PPG0 output modes.	49	39	34	K4
	RTO04_1 (PPG04_1)		19	-	-	-
	RTO05_0 (PPG04_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG04 when it is used in PPG0 output modes.	50	40	35	L1
	RTO05_1 (PPG04_1)		20	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Multi-Function Timer 1	DTTI1X_0	Input signal controlling waveform generator outputs RTO10 to RTO15 of Multi-Function Timer 1.	70	55	47	L5
	DTTI1X_1		94	-	-	-
	FRCK1_0	16-bit free-run timer ch 1 external clock input pin	71	56	48	M5
	FRCK1_1		78	63	-	K5
	IC10_0	16-bit input capture input pin of Multi-Function Timer 1. ICxx describes channel number.	96	79	63	L10
	IC10_1		95	-	-	-
	IC11_0		97	80	64	K10
	IC11_1		101	-	-	-
	IC12_0		98	81	65	M10
	IC12_1		102	-	-	-
	IC13_0		99	82	66	N11
	IC13_1		103	-	-	-
	RTO10_0 (PPG10_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG10 when it is used in PPG1 output modes.	56	46	38	N2
	RTO10_1 (PPG10_1)		85	70	-	N8
	RTO11_0 (PPG10_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG10 when it is used in PPG1 output modes.	57	47	39	N3
	RTO11_1 (PPG10_1)		86	71	-	M8
	RTO12_0 (PPG12_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG12 when it is used in PPG1 output modes.	58	48	40	M3
	RTO12_1 (PPG12_1)		87	72	-	N9
	RTO13_0 (PPG12_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG12 when it is used in PPG1 output modes.	59	49	41	L4
	RTO13_1 (PPG12_1)		88	73	-	P9
	RTO14_0 (PPG14_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG14 when it is used in PPG1 output modes.	60	50	42	M4
	RTO14_1 (PPG14_1)		89	74	-	M9
	RTO15_0 (PPG14_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG14 when it is used in PPG1 output modes.	61	51	43	N4
	RTO15_1 (PPG14_1)		90	75	-	L9

Latch-Up

Semiconductor devices are constructed by the formation of p-type and n-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic pnpn junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred milliamps to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

1. Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
2. Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

Fail-Safe Design

As previously mentioned, all semiconductor devices have inherent rates of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

6.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

6.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

1. Humidity

   Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

2. Discharge of static electricity

   When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

3. Corrosive gases, dust, or oil

   Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

4. Radiation, including cosmic radiation

   Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

5. Smoke, flame

   CAUTION: Plastic molded devices are flammable and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

11. Pin Status in Each CPU State

The terms used for pin status have the following meanings:

- INITX = 0

  This is the period when the INITX pin is at the L level.

- INITX = 1

  This is the period when the INITX pin is at the H level.

- SPL = 0

  This is the status that the standby pin level setting bit (SPL) in the standby mode control register (STB_CTL) is set to 0.

- SPL = 1

  This is the status that the standby pin level setting bit (SPL) in the standby mode control register (STB_CTL) is set to 1.

- Input enabled

  Indicates that the input function can be used.

- Internal input fixed at 0

  This is the status that the input function cannot be used. Internal input is fixed at L.

- Hi-Z

  Indicates that the pin drive transistor is disabled and the pin is put in the Hi-Z state.

- Setting disabled

  Indicates that the setting is disabled.

- Maintain previous state

  Maintains the state that was immediately prior to entering the current mode.
  If a built-in peripheral function is operating, the output follows the peripheral function.
  If the pin is being used as a port, that output is maintained.

- Analog input is enabled

  Indicates that the analog input is enabled.

- Trace output

  Indicates that the trace function can be used.

- GPIO selected

  In Deep standby mode, pins switch to the general-purpose I/O port.

- Setting prohibition

  Prohibition of a setting by specification limitation

Pin Status Type	Function Group	Power-On Reset or Low-Voltage Detection State	INITX Input State	Device Internal Reset State	Run mode or Sleep mode State	Timer mode, RTC mode, or Stop mode State		Deep Standby RTC Mode or Deep Standby Stop mode State		Return from Deep Standby Mode State
		Power Supply Unstable	Power Supply Stable		Power Supply Stable	Power Supply Stable		Power Supply Stable		Power Supply Stable
		-	INITX=0	INITX=1	INITX=1	INITX=1		INITX=1		INITX=1
		-	-	-	-	SPL=0	SPL=1	SPL=0	SPL=1	-
J	Analog output selected	Hi-Z	Hi-Z/ input enabled	Hi-Z/ input enabled	Maintain previous state	*2	*3	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	External interrupt enable selected					Maintain previous state	Maintain previous state			
	Resource other than above selected						Hi-Z/internal input fixed at 0			
	GPIO selected									
K	External interrupt enable selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z/ input enabled	Hi-Z/ input enabled			Hi-Z/internal input fixed at 0			
	GPIO selected									
L	Analog input selected	Hi-Z	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled	Hi-Z/ internal input fixed at 0/ analog input enabled
	Resource other than above selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	GPIO selected									

Pin Status Type	Function Group	Power-On Reset or Low-Voltage Detection State	INITX Input State	Device Internal Reset State	Run mode or Sleep mode State	Timer mode, RTC mode, or Stop mode State		Deep Standby RTC Mode or Deep Standby Stop mode State		Return from Deep Standby Mode State
		Power Supply Unstable	Power Supply Stable		Power Supply Stable	Power Supply Stable		Power Supply Stable		Power Supply Stable
		-	INITX=0	INITX=1	INITX=1	INITX=1		INITX=1		INITX=1
		-	-	-	-	SPL=0	SPL=1	SPL=0	SPL=1	-
Q	WKUP enabled	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	WKUP input enabled	Hi-Z/ WKUP input enabled	WKUP input enabled
	External interrupt enable selected							GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	Resource other than above selected	Hi-Z	Hi-Z/ input enabled	Hi-Z/ input enabled			Hi-Z/internal input fixed at 0			
	GPIO selected									
R	GPIO selected	Hi-Z	Hi-Z/ input enabled	Hi-Z/ input enabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	USB I/O pin	Setting disabled	Setting disabled	Setting disabled	Hi-Z at trans-mission/ input enabled/ internal input fixed at 0 at reception	Hi-Z at trans-mission/ input enabled/ internal input fixed at 0 at reception	Hi-Z at trans-mission/ input enabled/ internal input fixed at 0 at reception	Hi-Z/ input enabled	Hi-Z/ input enabled	Hi-Z/ input enabled

*1: Oscillation is stopped at sub Timer mode, sub CR Timer mode, RTC mode, Stop mode, Deep Standby RTC mode, and Deep Standby Stop mode.

*2: Maintain previous state at Timer mode. GPIO selected internal input fixed at 0 at RTC mode, Stop mode.

*3: Maintain previous state at Timer mode. Hi-Z/internal input fixed at 0 at RTC mode, Stop mode.

*4: It shows the case selected by EPFR14.E_SPLC register.

NAND Flash Mode

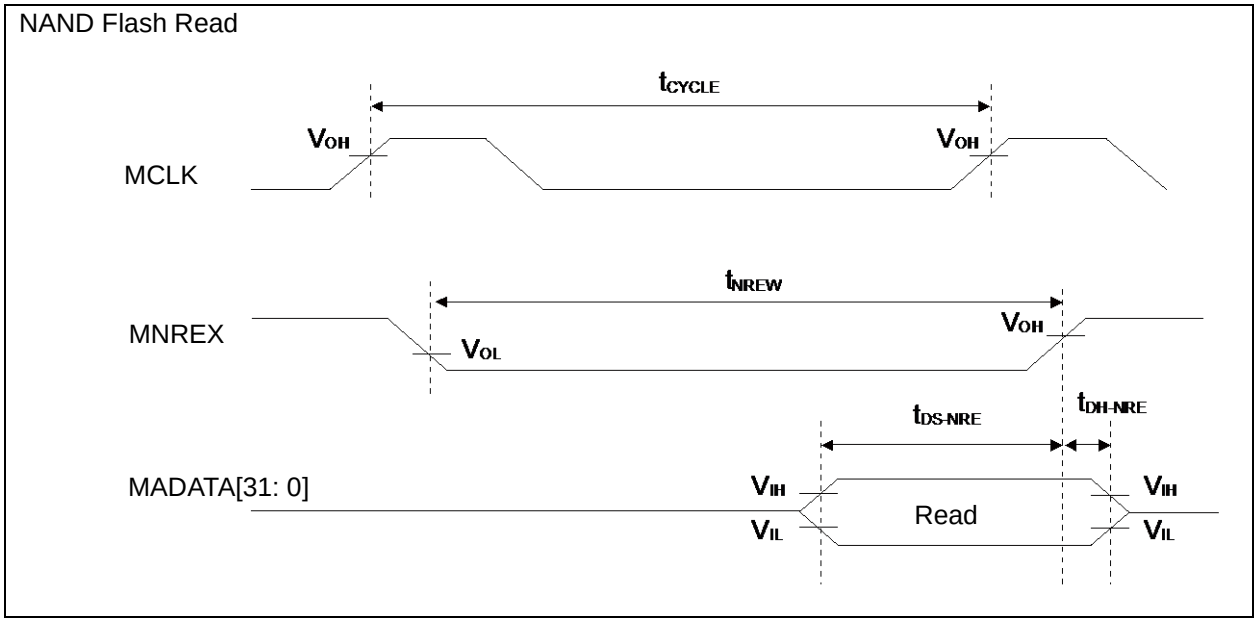
(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
MNREX Min pulse width	t_{NREW}	MNREX	-	MCLK×n-3	-	ns	
Data set up →MNREX ↑ time	t_{DS-NRE}	MNREX, MADATA[31: 0]	-	20	-	ns	
MNREX ↑ → Data hold time	t_{DH-NRE}	MNREX, MADATA[31: 0]	-	0	-	ns	
MNALE ↑ → MNWEX delay time	$t_{ALEH-NWEL}$	MNALE, MNWEX	-	MCLK×m-9	MCLK×m+9	ns	
MNALE ↓ → MNWEX delay time	$t_{ALEL-NWEL}$	MNALE, MNWEX	-	MCLK×m-9	MCLK×m+9	ns	
MNCLE ↑ → MNWEX delay time	$t_{CLEH-NWEL}$	MNCLE, MNWEX	-	MCLK×m-9	MCLK×m+9	ns	
MNWEX ↑ → MNCLE delay time	$t_{NWEH-CLEL}$	MNCLE, MNWEX	-	0	MCLK×m+9	ns	
MNWEX Min pulse width	t_{NWEW}	MNWEX	-	MCLK×n-3	-	ns	
MNWEX ↓ → Data output time	$t_{NWEL-DV}$	MNWEX, MADATA[31: 0]	-	-9	9	ns	
MNWEX ↑ → Data hold time	$t_{NWEH-DX}$	MNWEX, MADATA[31: 0]	-	0	MCLK×m+9	ns	

Note:

- *When the external load capacitance C_L = 30 pF (m = 0 to 15, n = 1 to 16)*

NAND Flash Read



12.4.12 CSIO (SPI) Timing

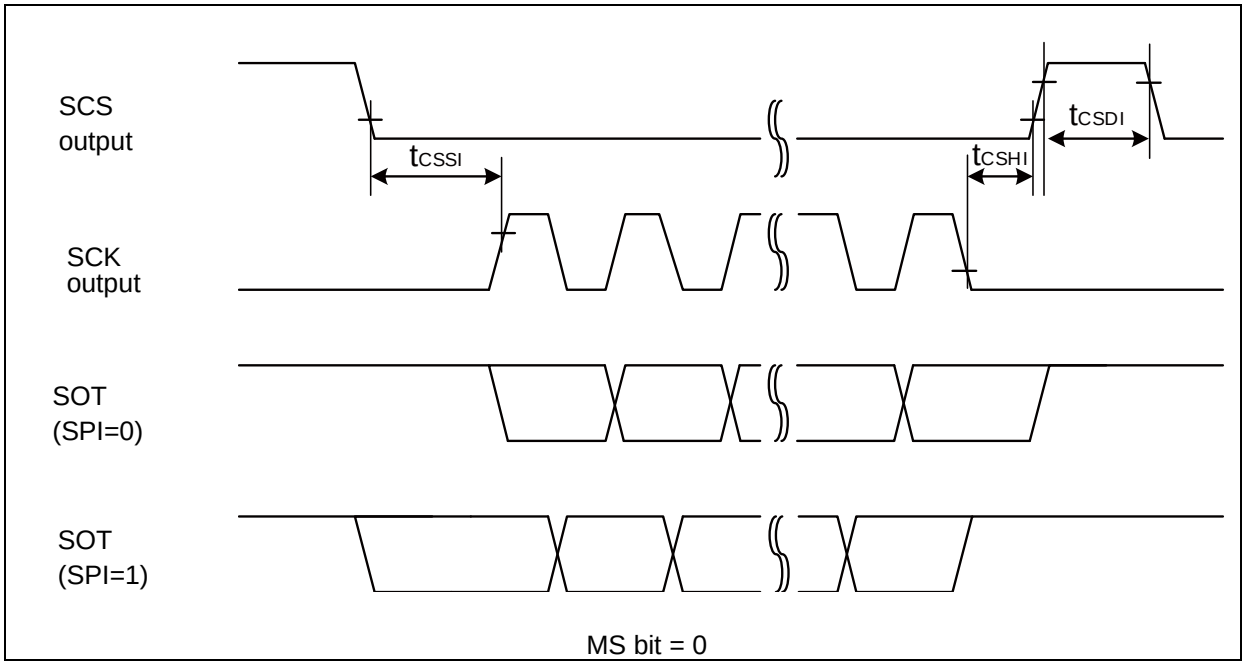
Synchronous Serial (SPI = 0, SCINV = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

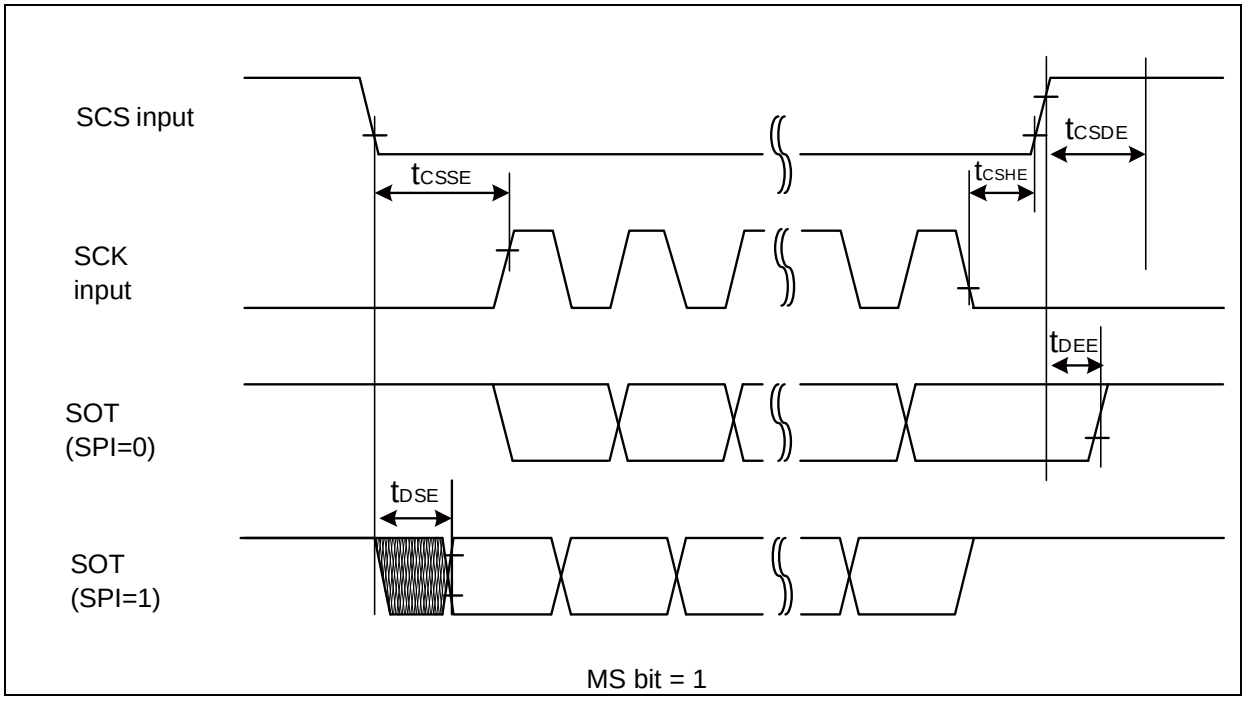
Parameter	Symbol	Pin Name	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Baud rate	-	-		-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Internal shift clock operation	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK↓→SOT delay time	t_{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN→SCK↑ setup time	t_{IVSHI}	SCKx, SINx		50	-	30	-	ns
SCK↑→SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	External shift clock operation	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK↓→SOT delay time	t_{SLOVE}	SCKx, SOTx		-	50	-	30	ns
SIN→SCK↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK↑→SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK fall time	tF	SCKx		-	5	-	5	ns
SCK rise time	tR	SCKx		-	5	-	5	ns

Notes:

- *The above characteristics apply to CLK synchronous mode.*
- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *These characteristics only guarantee the same relocate port number; for example, the combination of SCKx_0 and SOTx_1 is not guaranteed.*
- *When the external load capacitance C_L = 30 pF.*



MS bit = 0



MS bit = 1

When Using High-Speed Synchronous Serial Chip Select (SCINV = 0, CSLVL = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↓ setup time	t_{CSSI}	Internal shift clock operation	(*1)-20	(*1)+0	(*1)-20	(*1)+0	ns
SCK↑→SCS↑ hold time	t_{CSHI}		(*2)+0	(*2)+20	(*2)+0	(*2)+20	ns
SCS deselect time	t_{CSDI}		(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	ns
SCS↓→SCK↓ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCK↑→SCS↑ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCS↓→SOT delay time	t_{DSE}		-	25	-	25	ns
SCS↑→SOT delay time	t_{DEE}		0	-	0	-	ns

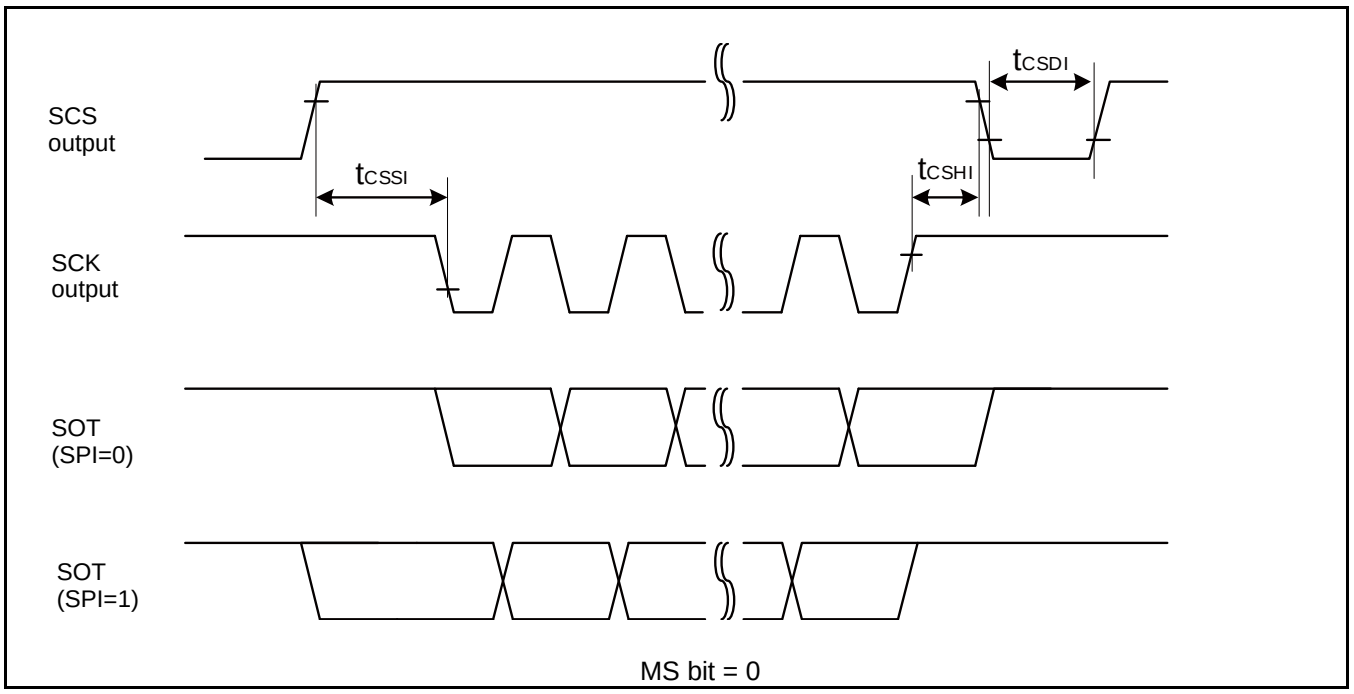
(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

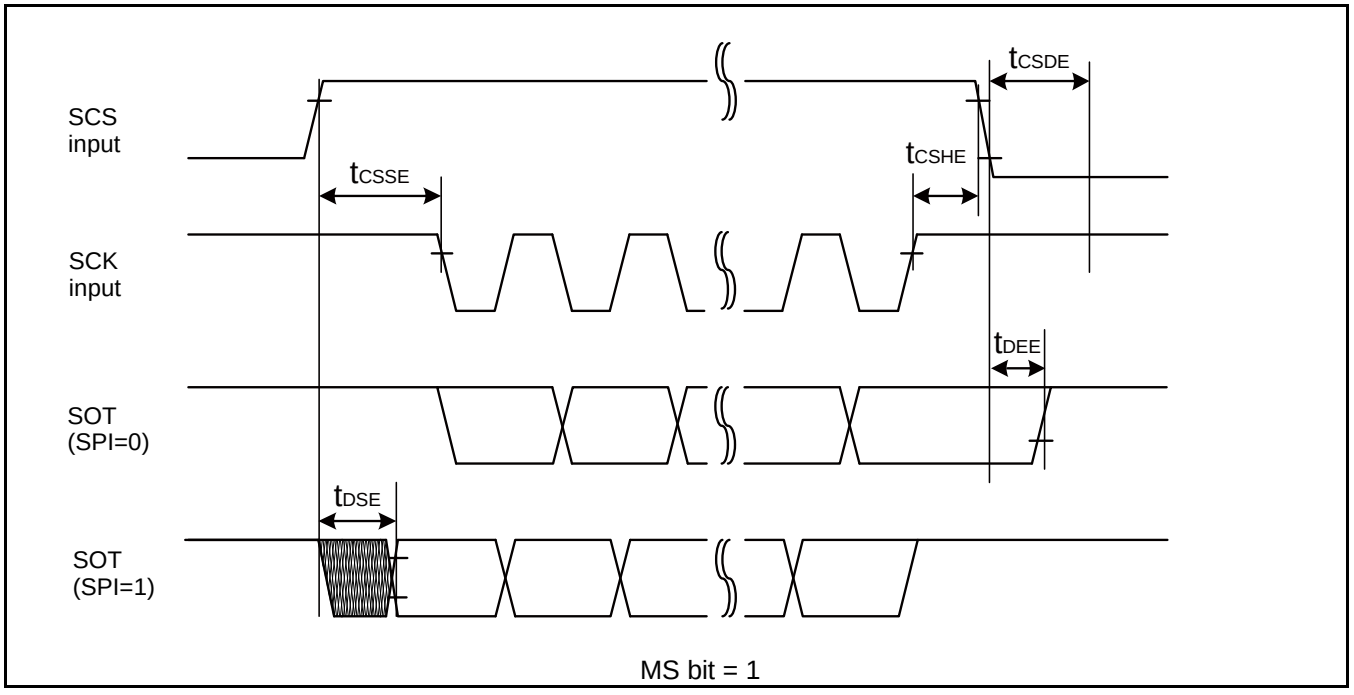
(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*

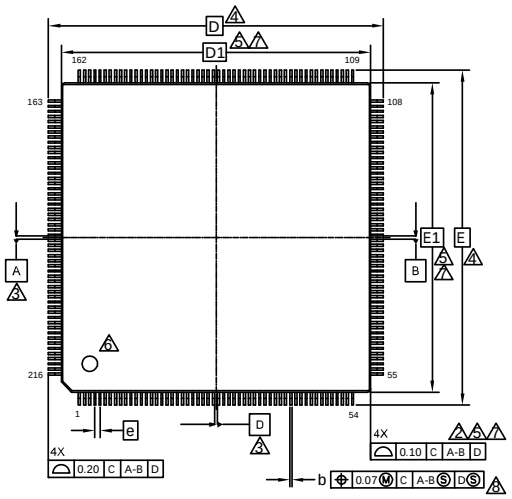


MS bit = 0

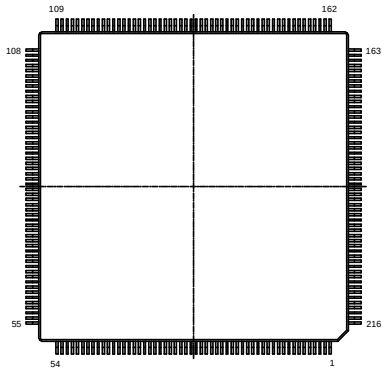


MS bit = 1

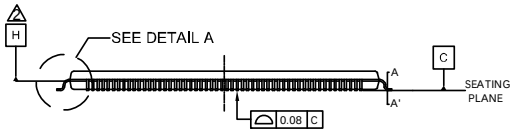
Package Type	Package Code
LQFP 216	LQQ 216



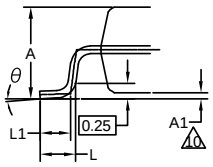
TOP VIEW



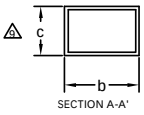
BOTTOM VIEW



SIDE VIEW



DETAIL A



SECTION A-A'

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.05	—	0.15
b	0.13	0.18	0.23
c	0.09	—	0.20
D	26.00 BSC.		
D1	24.00 BSC.		
e	0.40 BSC		
E	26.00 BSC.		
E1	24.00 BSC.		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°	—	8°

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-15153 **

PACKAGE OUTLINE, 216 LEAD LQFP
24.0X24.0X1.7 MM LQQ216 REV**

Document History

Document Title: S6E2C3 Series 32-bit ARM® Cortex®-M4F, FM4 Microcontroller
Document Number: 002-04988

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	-	AKIH	04/22/2015	New Spec.
*A	5126421	HITK	02/05/2016	Company name and layout design change. Added the note of TAP pin. Updated Package Code and Dimensions (LQFP-144, LQFP-176, LQFP-216).
*B	5634625	YSKA	02/20/2017	Deleted CAN in communications interfaces. (Page 1) Deleted CAN(RX0_2, TX0_2) in LQQ216 pin assignments (Page 12) Deleted RX2_0 in P7D in “4. Pin Descriptions” (Page 20) Updated 12.4.8 Power-On Reset Timing. Changed parameter from “Power Supply rise time(t_{VCCR})[ms]” to “Power ramp rate(dV/dt)[mV/us]” and add some comments. (Page 113) Modified CSIO timing typo (12.4.12 CSIO(SPI) Timing) Deleted “SPI=1, MS=0” in the titles and added MS=0,1 in the schematic (Page 134-141, 150-157) Modified RTC description(Features, Real-Time Clock(RTC)) Deleted “second , or day of the week” in the Interrupt function.(Page 3) Modifications related to the VBAT in the following chapter. “7. Handling Devices” Notes on Power-on (Page 76) “11. Pin Status in Each CPU State” List of VBAT Domain Pin Status (Page 90) “12.3.1 Current Rating” Table12-9. Typical and Maximum Current Consumption in Deep Standby STOP Mode, Deep Standby RTC Mode and VBAT (Page 105) Deleted MPNs below from “13. Ordering Information” (Page 190) S6E2C38H0AGV20000, S6E2C38J0AGB10000, S6E2C38J0AGV20000, S6E2C38L0AGL20000, S6E2C39H0AGV20000, S6E2C39J0AGB10000, S6E2C39J0AGV20000, S6E2C39L0AGL20000, S6E2C3AH0AGV20000, S6E2C3AJ0AGB10000, S6E2C3AJ0AGV20000, S6E2C3AL0AGL20000 Added MPNs below to “13. Ordering Information” (Page 190) S6E2C38H0AGV2000A, S6E2C38J0AGB1000A, S6E2C38J0AGV2000A, S6E2C38L0AGL2000A, S6E2C39H0AGV2000A, S6E2C39J0AGB1000A, S6E2C39J0AGV2000A, S6E2C39L0AGL2000A, S6E2C3AH0AGV2000A, S6E2C3AJ0AGB1000A, S6E2C3AJ0AGV2000A, S6E2C3AL0AGL2000A Deleted Baud rate spec for High-Speed Synchronous Serial in “12.4.12 CSIO(SPI) Timing”(Page 142-148) Modified the expression of the “Built-in CR” and add Note in the “1. Product Lineup”(Page 8) Modified typo(SCLKx_0 -> SCKx_0)(Page 126, 128, 130, 132) Change the name from “USB Function” to “USB Device” (Page 1, 8, 58) Added Maximum Access size in “Features”(Page 1) Updated IO circuit (type A) (Page 62)